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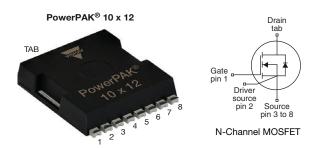
Vishay Siliconix

COMPLIANT

HALOGEN

FREE

EF Series Power MOSFET With Fast Body Diode



PRODUCT SUMMARY				
V _{DS} (V) at T _J max.	650			
R _{DS(on)} typ. (Ω) at 25 °C	$V_{GS} = 10 \text{ V}$	0.168		
Q _g max. (nC)	32			
Q _{gs} (nC)	7			
Q _{gd} (nC)	7			
Configuration	Single			

FEATURES

- 4th generation E series technology
- Low figure-of-merit (FOM) Ron x Qg
- Low effective capacitance (Co(er))
- Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- · Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	PowerPAK 10 x 12
Lead (Pb)-free and halogen-free	SiHK185N60EF-T1GE3

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V_{DS}	600	W	
Gate-source voltage			V_{GS}	± 30	V	
Continuous drain current (T _J = 150 °C)	V et 10 V	T _C = 25 °C		16	A	
	V _{GS} at 10 V	T _C = 100 °C	Ι _D	10		
Pulsed drain current ^a			I _{DM}	43		
Linear derating factor				0.9	W/°C	
Single pulse avalanche energy b			E _{AS}	24	mJ	
Maximum power dissipation			P_{D}	114	W	
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C	
Drain-source voltage slope	$T_{J} = $	T _J = 125 °C		100	V/ns	
Reverse diode dv/dt ^c			dv/dt	50	V/IIS	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 120 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 1.3 A
- c. $I_{SD} \le I_D$, di/dt = 700 A/ μ s, starting T_J = 25 °C



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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX. ^C	UNIT	
Maximum junction-to-ambient	R_{thJA}	-	55	°C/W	
Maximum junction-to-case (drain)	R_{thJC}	-	1.1	G/ VV	

PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT		
Static									
Drain-source breakdown voltage	V _{DS}	V _{GS} =	600	_	-	V			
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	Reference to 25 °C, I _D = 1 mA		0.69	-	V/°C		
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} =	- V _{GS} , I _D = 250 μA	3.0	-	5.0	V		
		V _{GS} = ± 20 V		V _{GS} = ± 20 V		-	-	± 100	nA
Gate-source leakage	I _{GSS}	,	V _{GS} = ± 30 V	-	-	± 1	μΑ		
		V _{DS} = 480 V, V _{GS} = 0 V		-	-	1	μΑ		
Zero gate voltage drain current	I _{DSS}	V _{DS} = 480 V	V _{DS} = 480 V, V _{GS} = 0 V, T _J = 125 °C		=	2	mA		
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 9.5 A	-	0.168	0.193	Ω		
Forward transconductance ^a	9 _{fs}	V _{DS} = 20 V, I _D = 9.5 A		-	5.4	-	S		
Dynamic									
Input capacitance	C _{iss}	$V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$ f = 1 MHz		-	1081	-	pF		
Output capacitance	C _{oss}			-	52	-			
Reverse transfer capacitance	C _{rss}			-	5	-			
Effective output capacitance, energy related ^a	C _{o(er)}	V _{DS} = 0 V to 480 V, V _{GS} = 0 V		-	40	-			
Effective output capacitance, time related ^b	C _{o(tr)}			-	247	-			
Total gate charge	Qg			-	21	32			
Gate-source charge	Q _{gs}	V _{GS} = 10 V	V _{GS} = 10 V I _D = 9.5 A, V _{DS} = 480 V	-	7	-	nC		
Gate-drain charge	Q _{gd}	7			7	-	1		
Turn-on delay time	t _{d(on)}	$V_{DD} = 480 \text{ V}, I_{D} = 9.5 \text{ A}, V_{GS} = 10 \text{ V}, R_{g} = 9.1 \Omega$		-	14	28			
Rise time	t _r			-	23	46			
Turn-off delay time	t _{d(off)}			-	25	50	ns		
Fall time	t _f			-	16	32			
Gate input resistance	R_g	f = 1 MHz		0.3	0.7	1.4	Ω		
Drain-Source Body Diode Characteristic	s						•		
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	16			
Pulsed diode forward current	I _{SM}			-	-	43	- A		
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 9.5 A, V _{GS} = 0 V		-	-	1.2	V		
Reverse recovery time	t _{rr}	$T_J = 25 \text{ °C}, I_F = I_S = 9.5 \text{ A},$ $di/dt = 100 \text{ A/}\mu\text{s}, V_R = 400 \text{ V}$		-	111	222	ns		
Reverse recovery charge	Q _{rr}			-	0.6	1.2	μC		
Reverse recovery current	I _{RRM}			_	10	_	Α		

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}
- b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}
- c. When mounted on 1" x 1" FR4 board



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

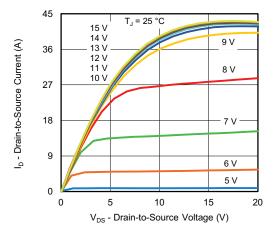


Fig. 1 - Typical Output Characteristics

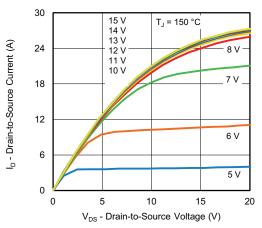


Fig. 2 - Typical Output Characteristics

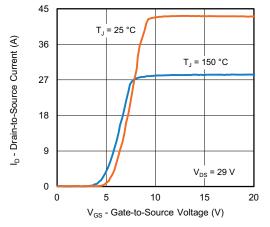


Fig. 3 - Typical Transfer Characteristics

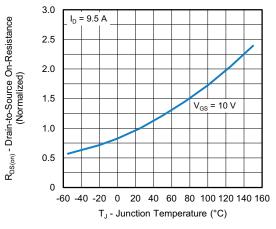


Fig. 4 - Normalized On-Resistance vs. Temperature

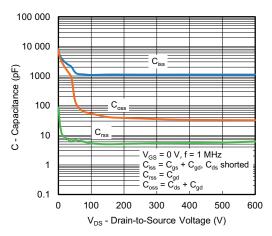


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

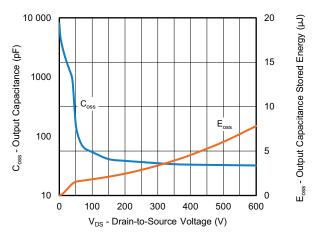


Fig. 6 - Coss and Eoss vs. VDS



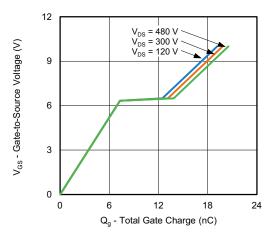


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

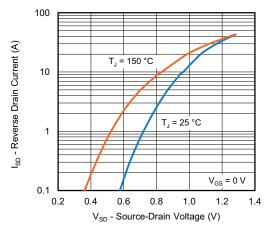


Fig. 8 - Typical Source-Drain Diode Forward Voltage

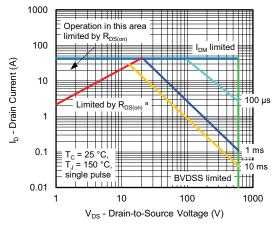


Fig. 9 - Maximum Safe Operating Area

Note

a. V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

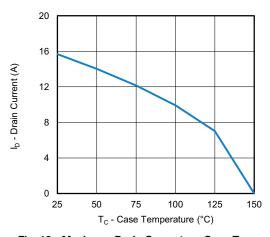


Fig. 10 - Maximum Drain Current vs. Case Temperature

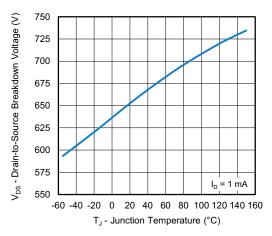


Fig. 11 - Temperature vs. Drain-to-Source Voltage



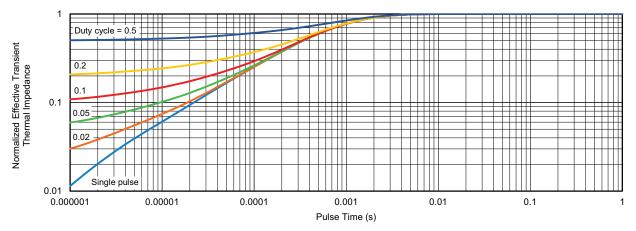


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

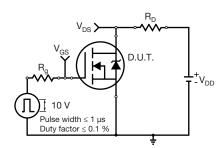


Fig. 13 - Switching Time Test Circuit

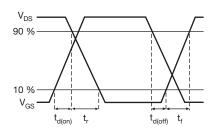


Fig. 14 - Switching Time Waveforms

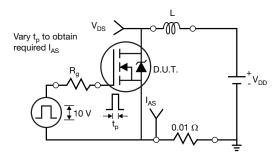


Fig. 15 - Unclamped Inductive Test Circuit

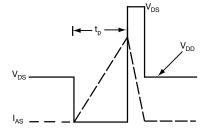


Fig. 16 - Unclamped Inductive Waveforms

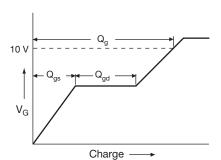


Fig. 17 - Basic Gate Charge Waveform

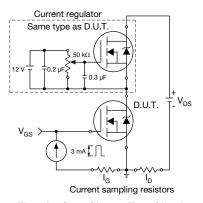
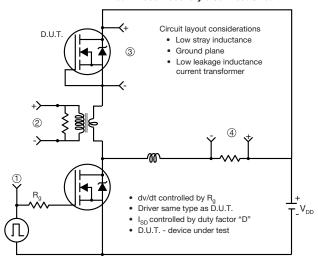


Fig. 18 - Gate Charge Test Circuit

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Peak Diode Recovery dv/dt Test Circuit



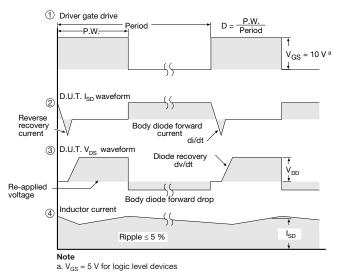
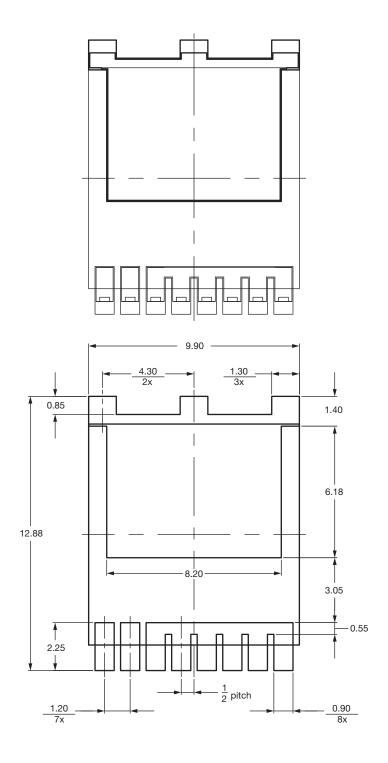


Fig. 19 - For N-Channel

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Recommended Land Pattern PowerPAK® 10 x 12 (TOLL) (High Voltage)



Note

• Dimensions in mm

ECN: S22-1061-Rev. C, 26-Dec-2022

DWG: 3013



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